Silicon Carbide Schottky Diode

650 V, 40 A

Description

Silicon Carbide (SiC) Schottky Diodes use a completely new technology that provides superior switching performance and higher reliability compared to Silicon. No reverse recovery current, temperature independent switching characteristics, and excellent thermal performance sets Silicon Carbide as the next generation of power semiconductor. System benefits include highest efficiency, faster operating frequency, increased power density, reduced EMI, and reduced system size & cost.

Features

- Max Junction Temperature 175°C
- Avalanche Rated 94 mJ
- High Surge Current Capacity
- Positive Temperature Coefficient
- Ease of Paralleling
- No Reverse Recovery/No Forward Recovery
- AEC-Q101 Qualified
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant

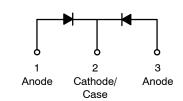
Applications

- Automotive HEV-EV Onboard Chargers
- Automotive HEV-EV DC-DC Converters

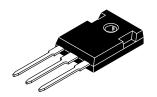


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Schottky Diode



TO-247-3LD CASE 340CX

MARKING DIAGRAM



\$Y = ON Semiconductor Logo &Z = Assembly Plant Code &3 = Numeric Date Code &K = Lot Code

FFSH4065BDN = Specific Device Code

ORDERING INFORMATION

See detailed ordering and shipping information on page 2 of this data sheet.

ABSOLUTE MAXIMUM RATINGS ($T_C = 25$ °C unless otherwise noted)

Symbol	Parameter		Value	Unit
V_{RRM}	Peak Repetitive Reverse Voltage		650	V
E _{AS}	Single Pulse Avalanche Energy (Note 1)		94*	mJ
I _F	Continuous Rectified Forward Current @ T _C < 136°C		20*/40**	Α
I _{F, Max}	Non-Repetitive Peak Forward Surge Current	T _C = 25°C, 10 μs	889	Α
		T _C = 150°C, 10 μs	861	Α
I _{F,SM}	Non-Repetitive Forward Surge Current $T_C = 25^{\circ}C$	Half-Sine Pulse, t _p = 8.3 ms	84	А
Ptot	Power Dissipation	T _C = 25°C	127	W
		T _C = 150°C	21	W
T _J , T _{STG}	Operating and Storage Temperature Range		-55 to +175	°C
	TO247 Mounting Torque, M3 Screw		60	Ncm

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

* Per Leg, ** Per Device

THERMAL CHARACTERISTICS

Symbol	Parameter	Value	Unit
R _{θJC} Thermal Resistance, Junction to Case, Max		1.17*/0.58**	°C/W

^{*} Per Leg, ** Per Device

ELECTRICAL CHARACTERISTICS ($T_C = 25$ °C unless otherwise noted (per leg))

Symbol	Parameter	Test Condition	Min	Тур	Max	Unit
V_{F}	Forward Voltage	I _F = 20 A, T _C = 25°C	_	1.38	1.7	V
		I _F = 20 A, T _C = 125°C	_	1.6	2.0	
		I _F = 20 A, T _C = 175°C	-	1.72	2.4	
I _R	Reverse Current	V _R = 650 V, T _C = 25°C	-	0.5	40	μΑ
		V _R = 650 V, T _C = 125°C	-	1	80	
		V _R = 650 V, T _C = 175°C	-	2	160	
Q _C	Total Capacitive Charge	V = 400 V	-	51	=	nC
С	Total Capacitance	V _R = 1 V, f = 100 kHz	-	866	_	pF
		V _R = 300 V, f = 100 kHz	-	80	-	
		V _R = 600 V, f = 100 kHz	-	70	-	

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

PACKAGE MARKING AND ORDERING INFORMATION

Part Number	Top Marking	Package	Shipping
FFSH4065BDN-F085	FFSH4065BDN	TO-247-3LD (Pb-Free / Halogen Free)	30 Units / Tube

^{1.} E_{AS} of 94 mJ is based on starting T_J = 25°C, L = 0.5 mH, I_{AS} = 19.4 A, V = 50 V.

TYPICAL CHARACTERISTICS

 $(T_J = 25^{\circ}C \text{ unless otherwise noted (per leg)})$

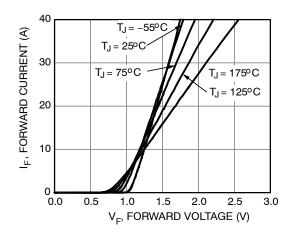


Figure 1. Forward Characteristics

Figure 2. Reverse Characteristics

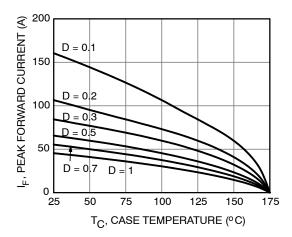


Figure 3. Current Derating

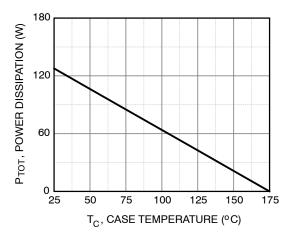


Figure 4. Power Derating

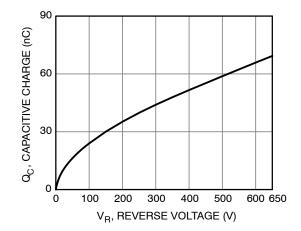


Figure 5. Capacitive Charge vs. Reverse Voltage

TYPICAL CHARACTERISTICS

 $(T_J = 25^{\circ}C \text{ unless otherwise noted})$

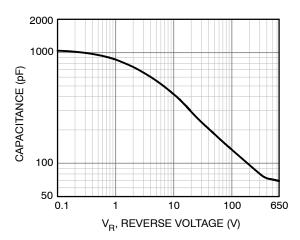


Figure 6. Capacitance vs. Reverse Voltage

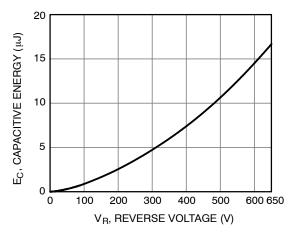


Figure 7. Capacitance Stored Energy

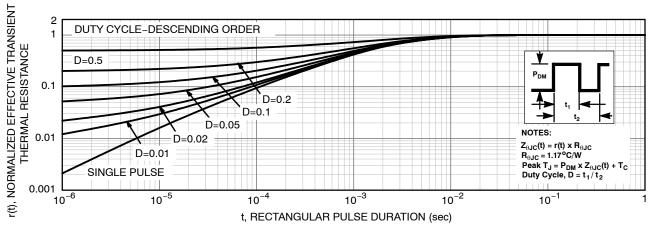


Figure 8. Junction-to-Case Transient Thermal Response Curve

TEST CIRCUIT AND WAVEFORMS

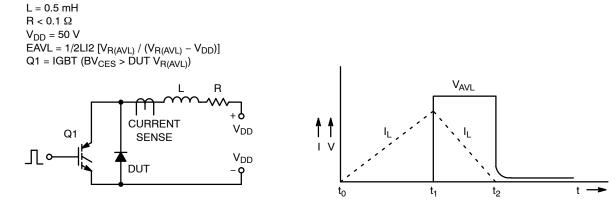
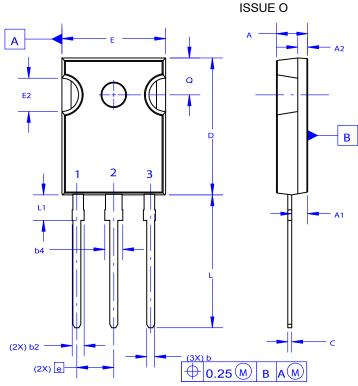


Figure 9. Unclamped Inductive Switching Test Circuit & Waveform

PACKAGE DIMENSIONS

TO-247-3LD CASE 340CX

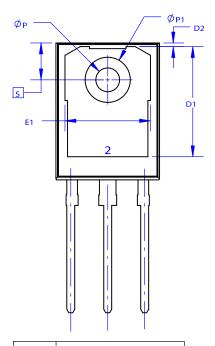


NOTES: UNLESS OTHERWISE SPECIFIED.

- A. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.

 B. ALL DIMENSIONS ARE IN MILLIMETERS.

- C. DRAWING CONFORMS TO ASME Y14.5 2009.
 D. DIMENSION A1 TO BE MEASURED IN THE REGION DEFINED BY L1.
- E. LEAD FINISH IS UNCONTROLLED IN THE REGION DEFINED BY L1.



DIM	MILLIMETERS				
DIM	MIN	NOM	MAX		
Α	4.58	4.70	4.82		
A 1	2.20	2.40	2.60		
A2	1.40	1.50	1.60		
D	20.32	20.57	20.82		
Е	15.37	15.62	15.87		
E2	4.96	5.08	5.20		
е	~	5.56	~		
L	19.75	20.00	20.25		
L1	3.69	3.81	3.93		
ØΡ	3.51	3.58	3.65		
Q	5.34	5.46	5.58		
S	5.34	5.46	5.58		
b	1.17	1.26	1.35		
b2	1.53	1.65	1.77		
b4	2.42	2.54	2.66		
С	0.51	0.61	0.71		
D1	13.08	~	~		
D2	0.51	0.93	1.35		
E1	12.81	~	~		
ØP1	6.60	6.80	7.00		

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